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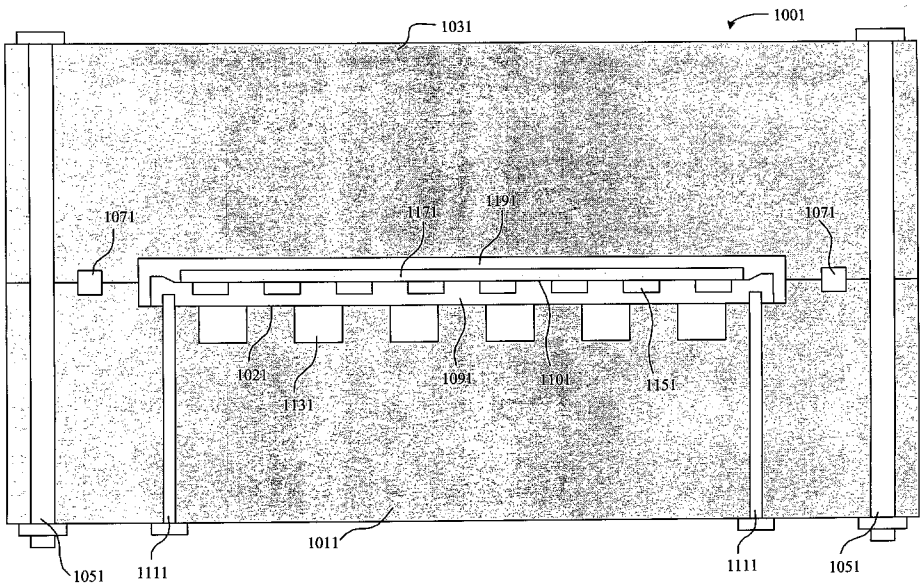
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(54) Title: CHAMBER AND ASSOCIATED METHODS FOR WAFER PROCESSING



(57) Abstract: A wafer processing chamber is provided for allowing a fluid flow and a fluid pressure within the chamber to be controlled in a variable manner. The chamber utilizes removable plates that can be configured to control the fluid flow and the fluid pressure in an inner volume within the chamber. Also, the removable plates can be used to separate the inner volume within the chamber from an outer volume within the chamber. Additionally, a wafer clamping apparatus is provided for use in the chamber. The wafer clamping apparatus uses a pressure differential between a top surface and a bottom surface of the wafer to pull the wafer toward a wafer support structure in contact with the wafer bottom surface, whereby the wafer is secured and maintained in an immobile state. Furthermore, high-pressure chamber configurations are provided.

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